

Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

HPE 5945 4-slot Switch JQ076A

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing		0

Item Description	Notes	Quantity of items included in product
radioactive substances		
2.0 Tools Required		

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Phillips screwdriver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove all the blank panel.
2. Remove film 1-1 from panel 1-2.
3. Remove shielding fingers 2-1 from panel 2-2.
4. Unscrew all screws 3, then remove the cover assembly 4 and management panel 5.
5. Remove lab 4-3,4-4,4-5,4-6 and foam 4-2 from cover 4-1.
6. Remove film 5-1 and film 5-3 from panel 5-2.
7. Unscrew all screws 6 and screws 7, then remove the pcb 8,10,11 and air guide 9.
8. Remove dowel 8-1, dowel bushing 8-2, spring 8-3 and radiator 8-4 from pcb 8-5.
9. Unscrew all screws 10-1, then separation of pcb 10-2 and pcb 10-4, then remove the double-screw belts 10-3.
10. Unscrew all screws 11-5, then separation of pcb 11-6 and pcb 11-7, then remove dowel 11-1, dowel bushing 11-2, spring 11-3 and radiator 11-4 from pcb 11-7.
11. Unscrew all double-screw belts 12 and radiator's screws, then remove radiator 13 and pcb 14.
12. Unscrew all screws 14-1, then remove handle 14-2 from pcb 14-3.
13. Unscrew all screws 15 and screws 17, then remove film 16 and support panel 18.
14. Unscrew all screws 19 and double-screw belts 21, then remove rack 20 and pcb 22.
15. Unscrew all screws 22-1, then remove confluence bar 22-2 from pcb 22-3.
16. Separation of film 23,27, shielding fingers 24, foam 25 and conductive foam 26 from base 28.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

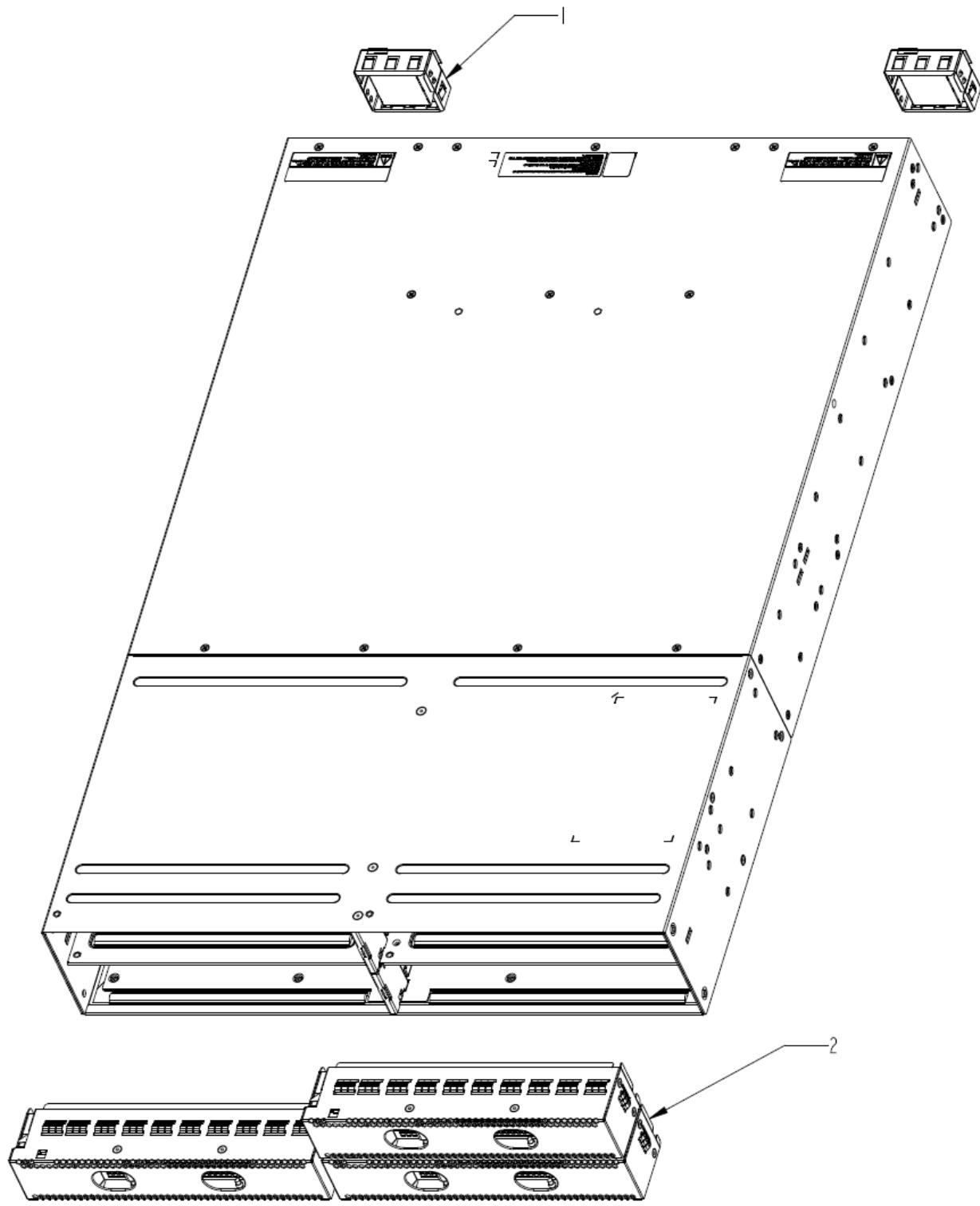


Figure 1 Remove all the blank panel

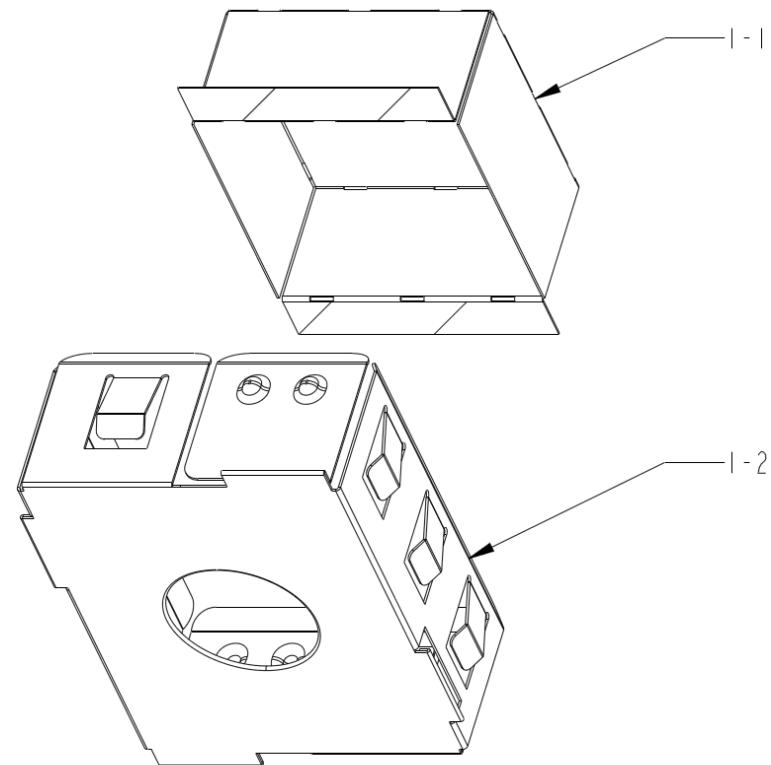


Figure 2 Treatments to the power blank panel

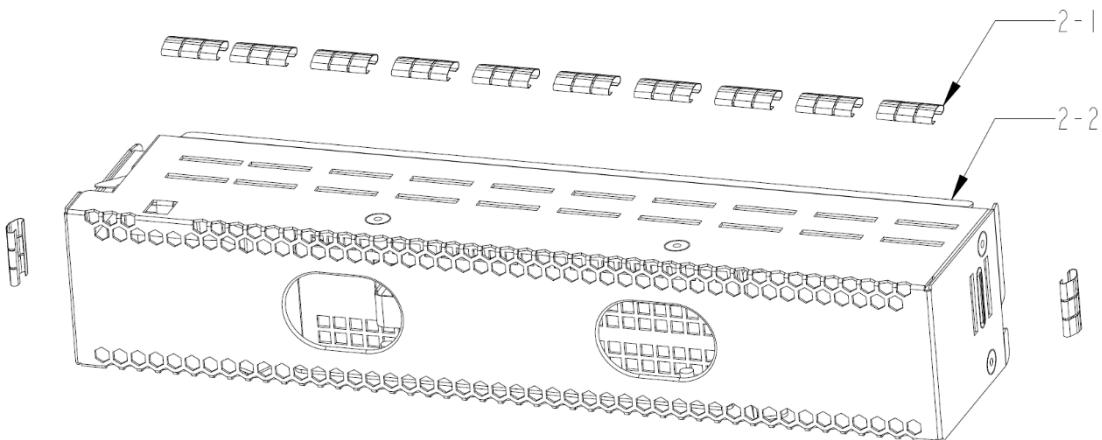


Figure 3 Treatments to the card blank panel

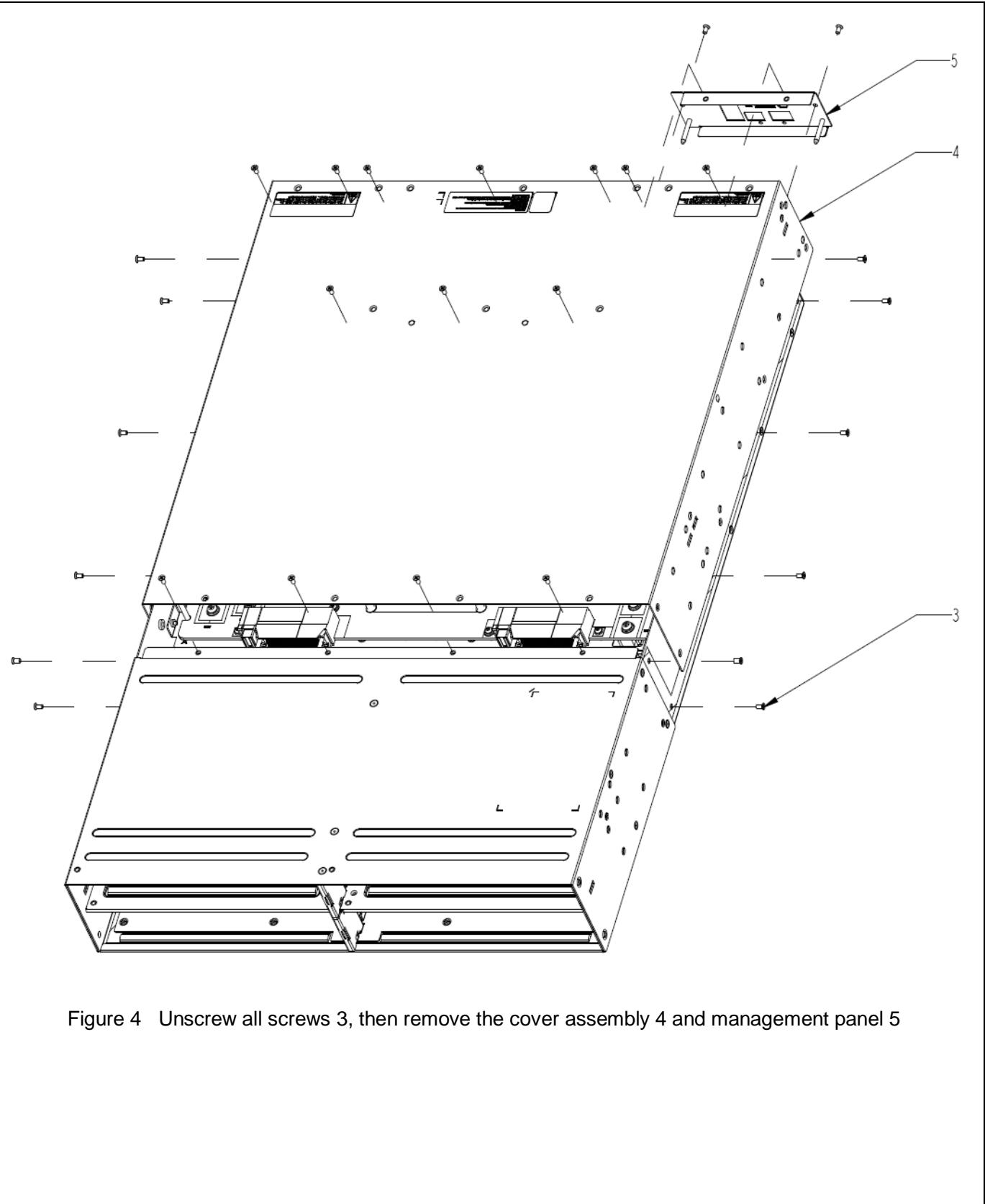


Figure 4 Unscrew all screws 3, then remove the cover assembly 4 and management panel 5

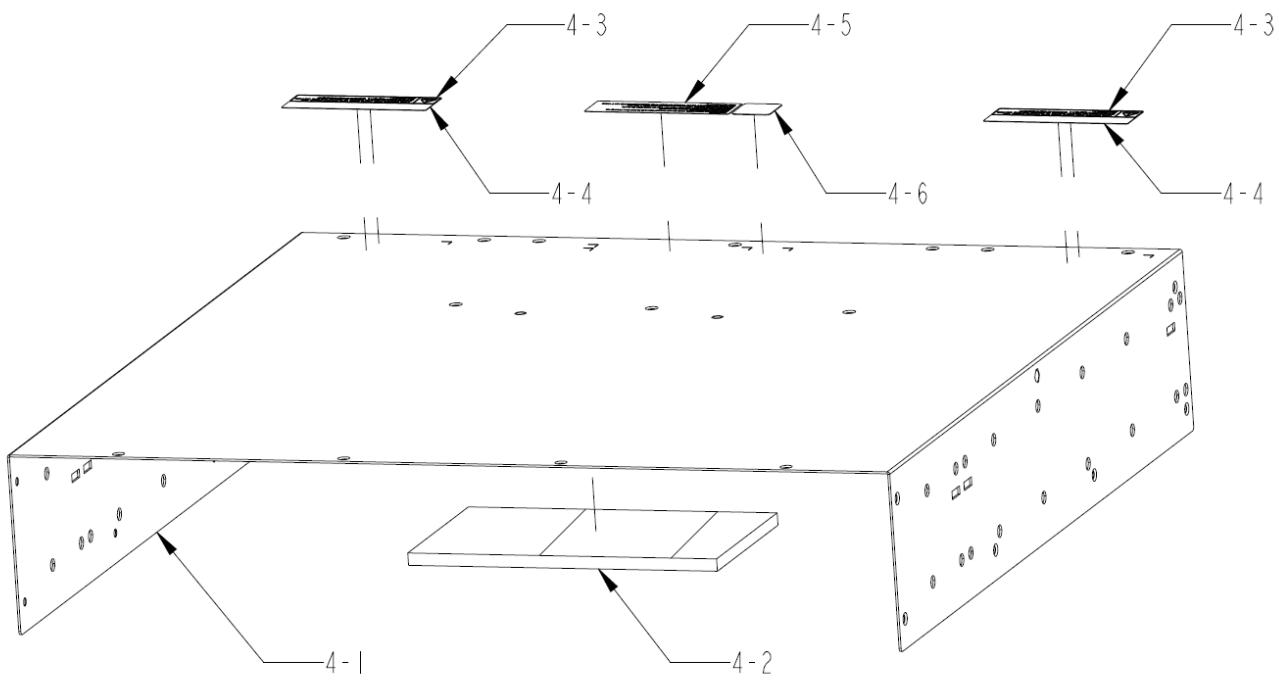


Figure 5 Remove lab 4-3,4-4,4-5,4-6 and foam 4-2 from cover 4-1

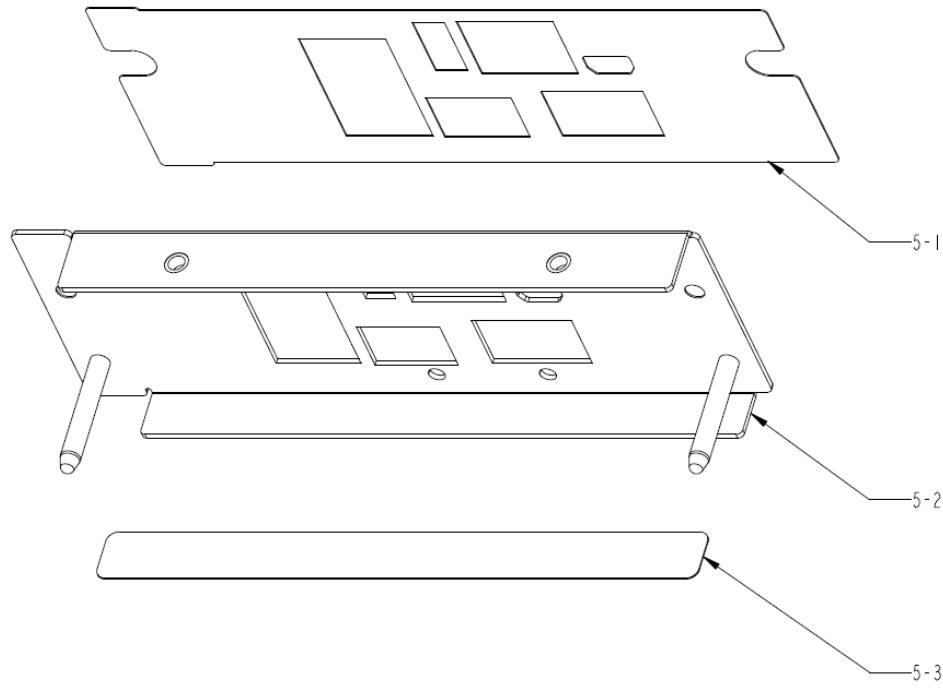


Figure 6 Remove film 5-1 and film 5-3 from panel 5-2

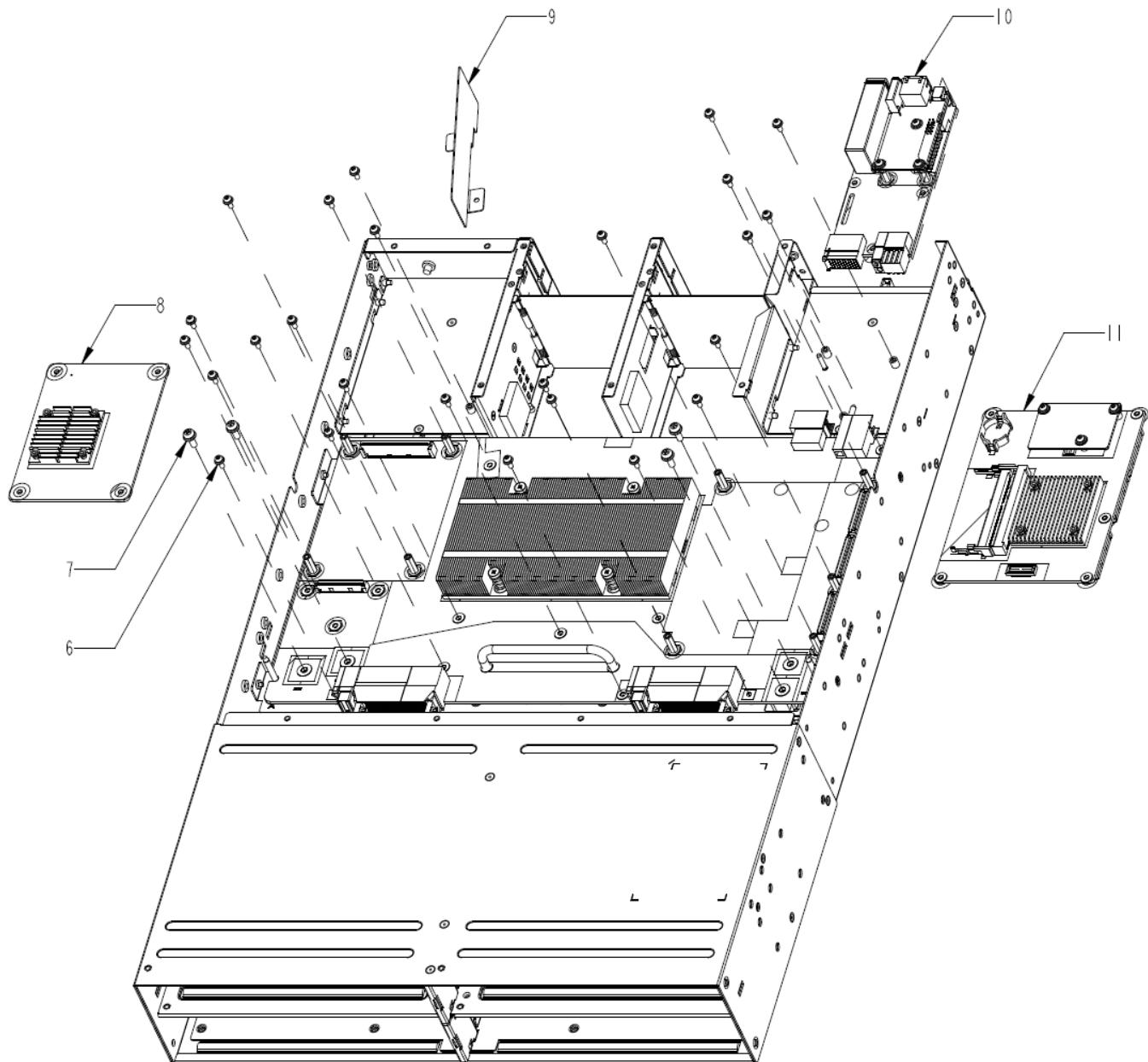


Figure 7 Unscrew all screws 6 and screws 7, then remove the pcb 8,10,11 and air guide 9

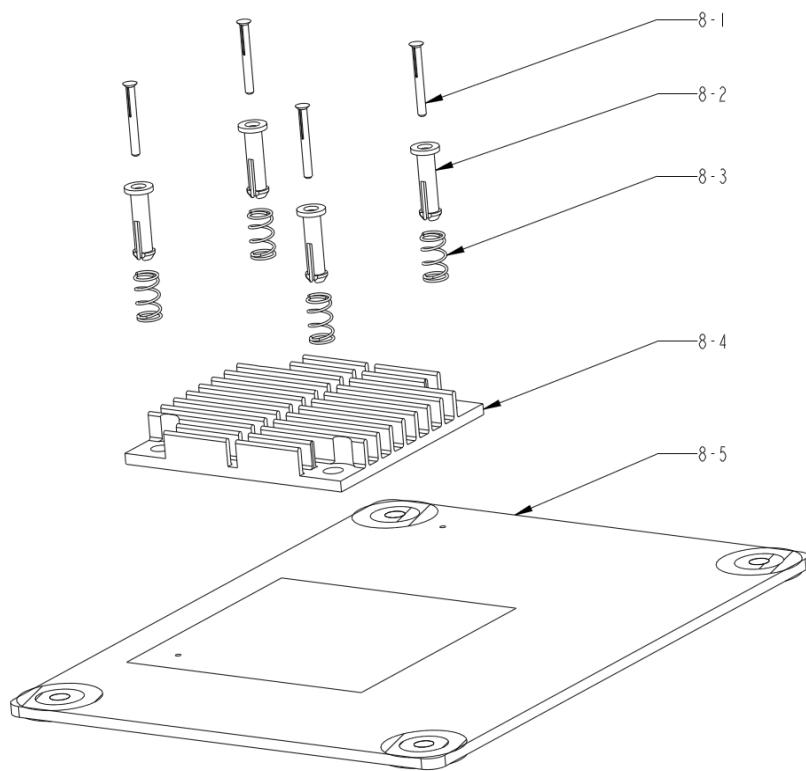


Figure 8 Remove dowel 8-1, dowel bushing 8-2, spring 8-3 and radiator 8-4 from pcb 8-5

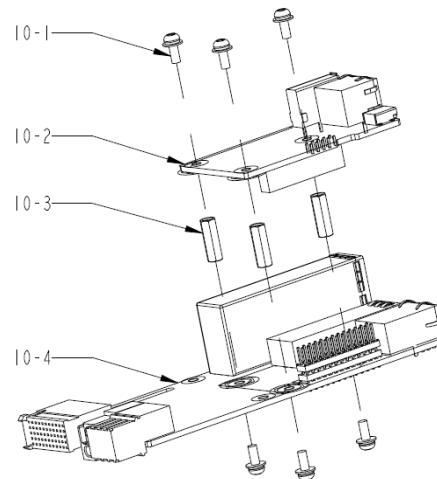


Figure 9 Unscrew all screws 10-1, then separation of pcb 10-2 and pcb 10-4, then remove the double-screw belts 10-3

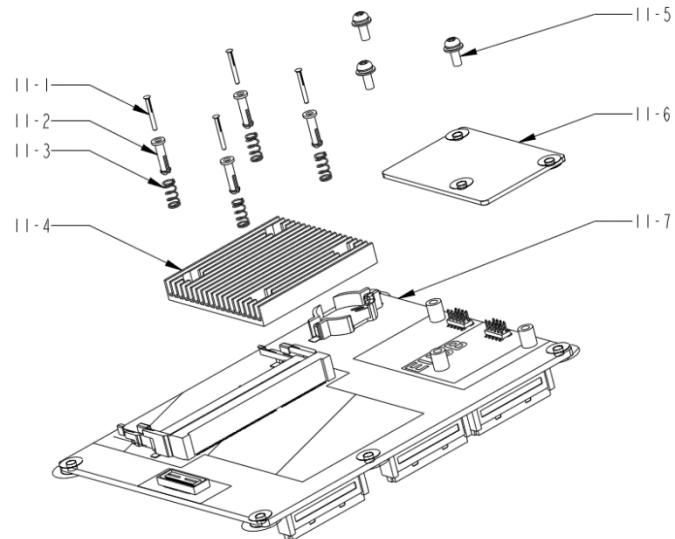


Figure 10 Unscrew all screws 11-5, then separation of pcb 11-6 and pcb 11-7, then remove dowel 11-1, dowel bushing 11-2, spring 11-3 and radiator 11-4 from pcb 11-7

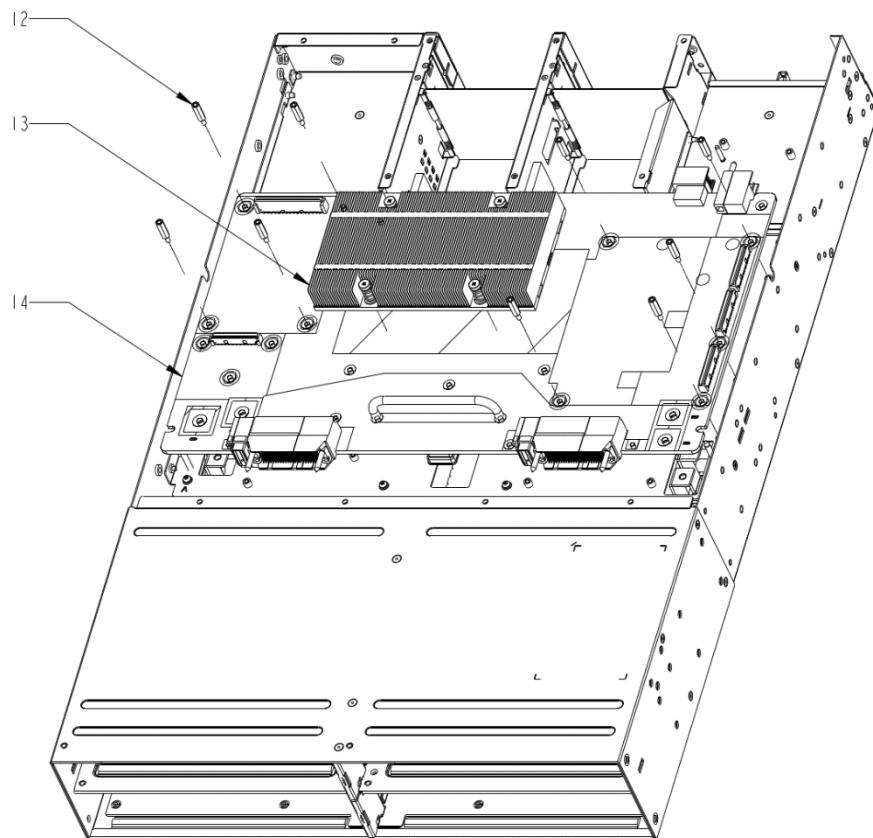


Figure 11 Unscrew all double-screw belts 12 and radiator's screws, then remove radiator 13 and pcb 14

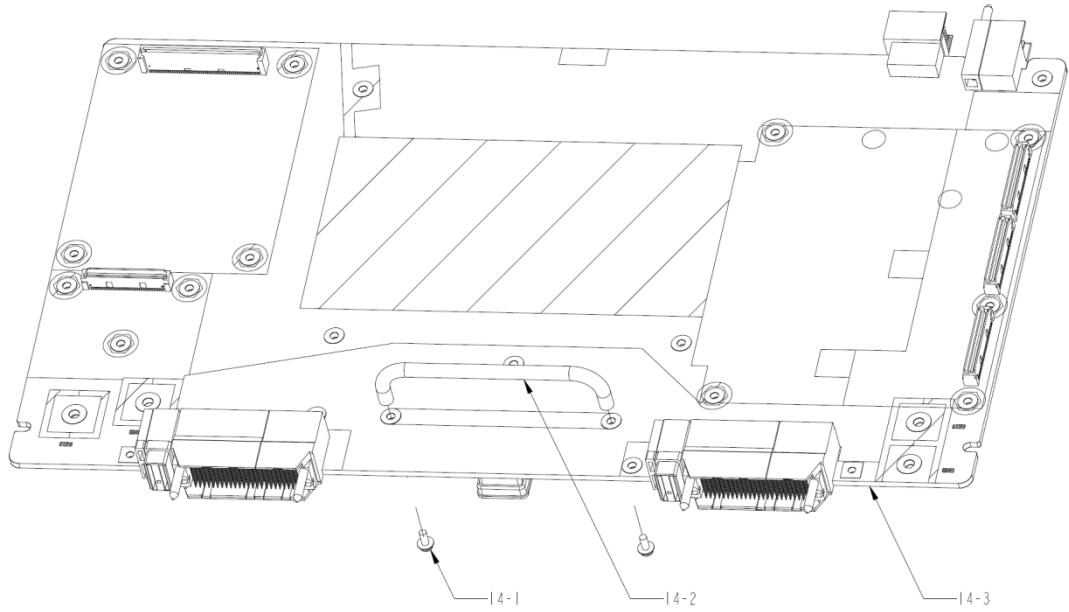


Figure 12 Unscrew all screws 14-1, then remove handle 14-2 from pcb 14-3

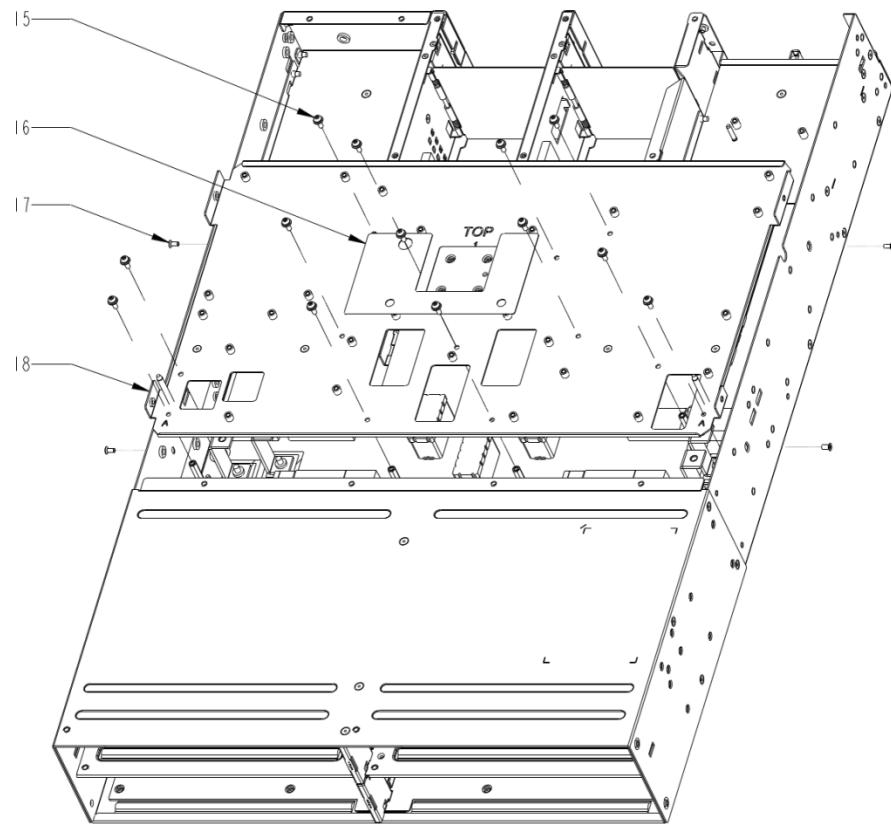


Figure 13 Unscrew all screws 15 and screws 17, then remove film 16 and support panel 18

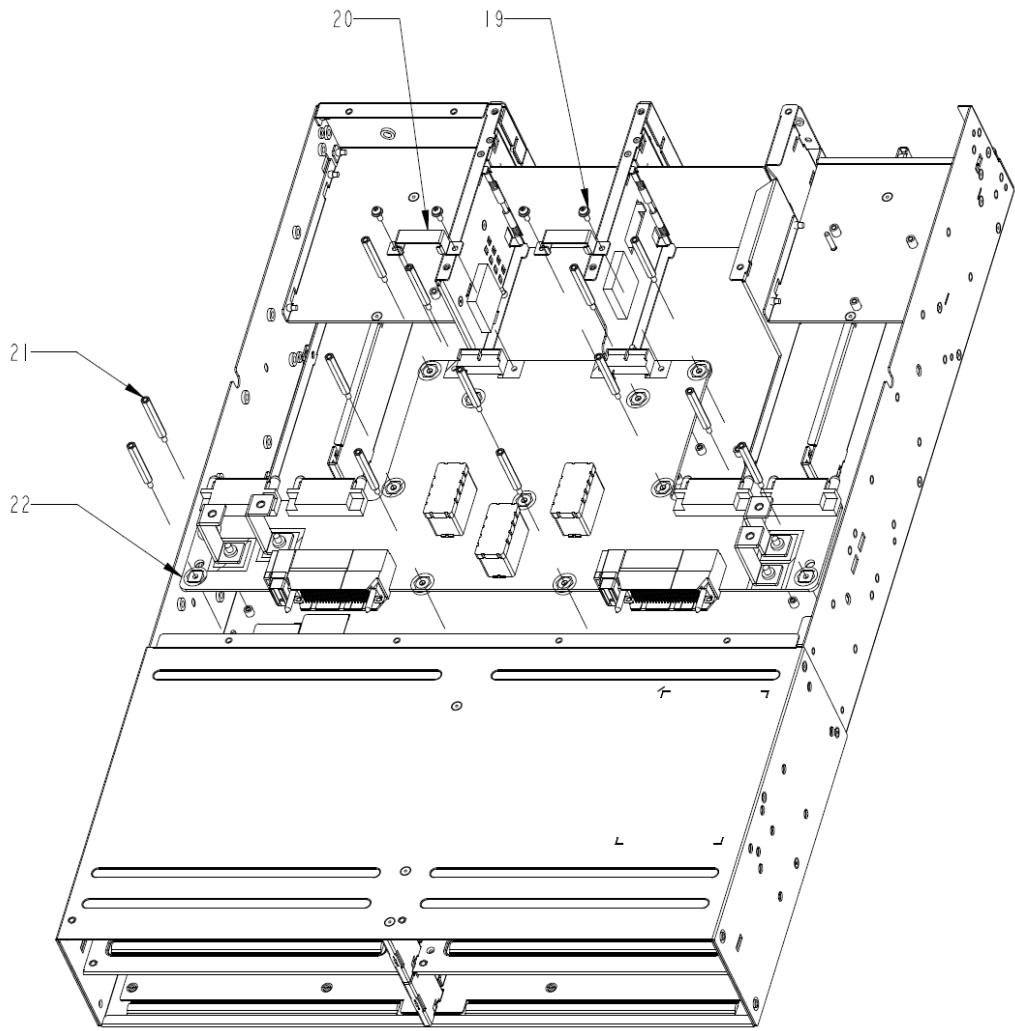


Figure 14 Unscrew all screws 19 and double-screw belts 21, then remove rack 20 and pcb 22

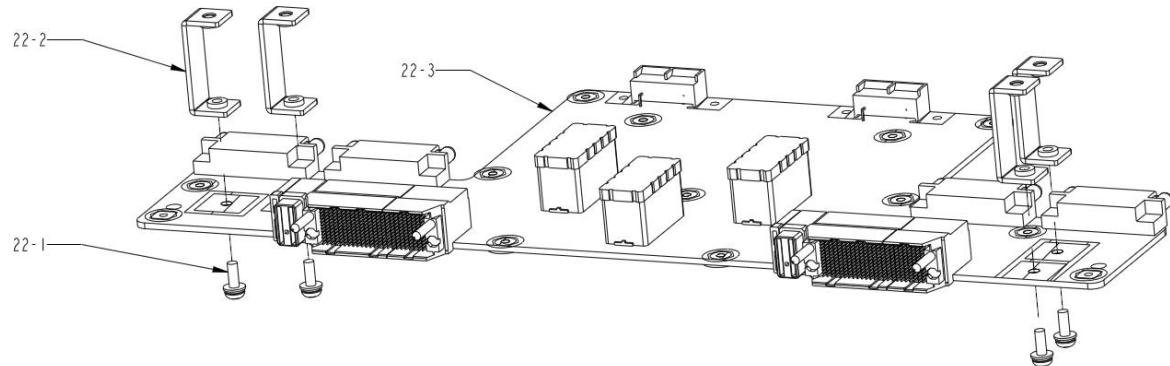


Figure 15 Unscrew all screws 22-1, then remove confluence bar 22-2 from pcb 22-3

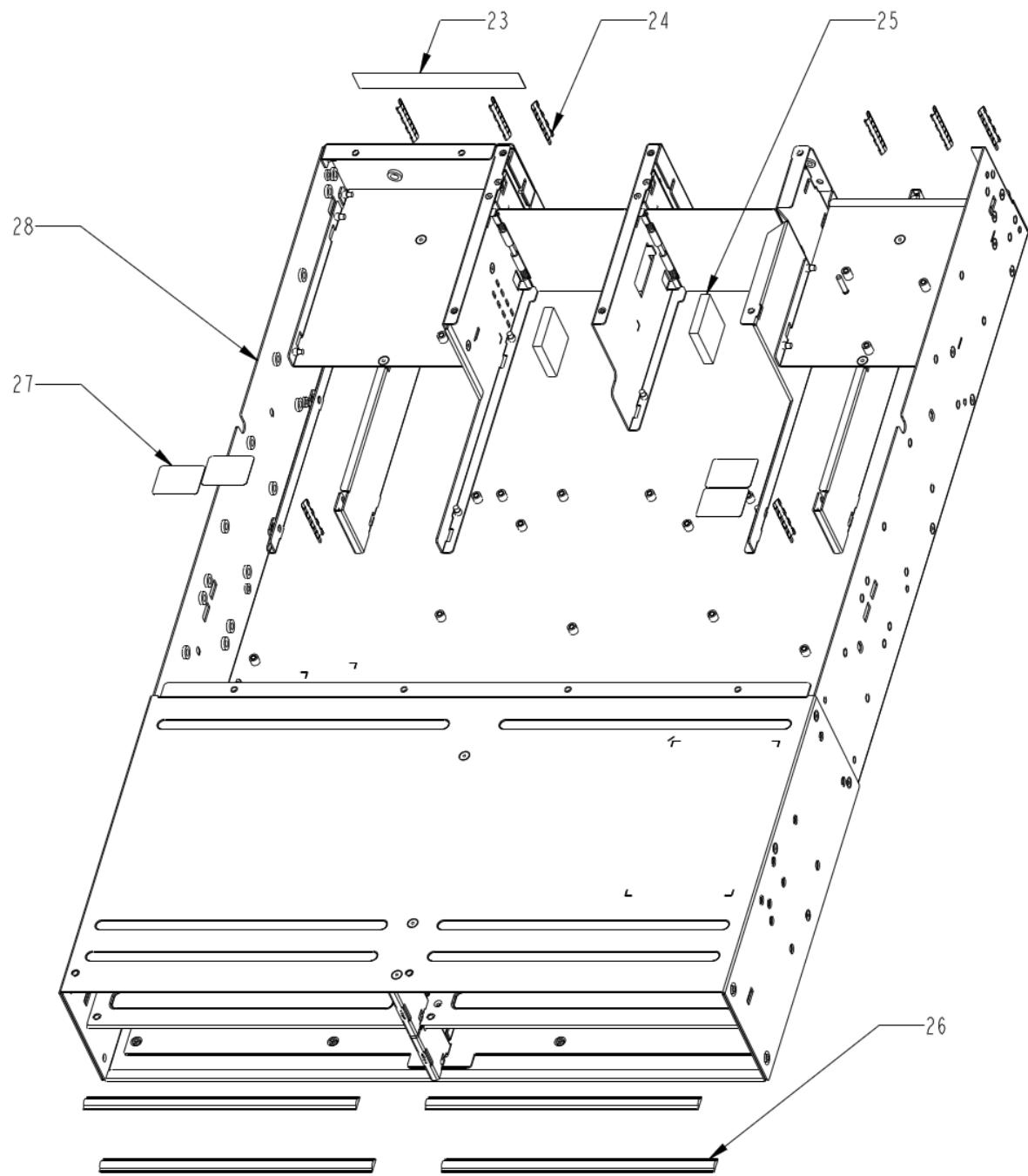


Figure 16 Separation of film 23,27, shielding fingers 24, foam 25 and conductive foam 26 from base 28